

# DDR3

The Global Leader in Specialized Storage and Memory Solutions



### **KEY FEATURES**

- Density: 1 GB to 16 GB
- Chipkill support
- Fly-by command/address/control bus with on-DIMM termination
- Higher bandwidth performance, effectively up to 1866 MT/s
- Better performance at low power;
  1.5V (Normal) and 1.35V (Low Voltage)

Operating at 1.5V (normal) and 1.35V (low voltage) and with a transfer speed of up to 1866 MT/s, ATP DDR3 modules deliver better performance while consuming significantly less power than DDR2 memory. ATP DDR3 modules are supported by the Intel® Core™ i7 Series, the AMD AM3 Phenom™ processor, and the latest AMD Embedded Enterprise Chipsets. DDR3 modules are not pin-compatible with the prior-generation modules and have alignment notches preventing them from being inserted into incompatible slots.

ATP offers DDR3 SDRAMs in a wide range of form factors and features including SO-DIMM and Mini-DIMM with low profile, very low profile (VLP) and ultra-low profile (ULP) options.

In addition to standard offerings, ATP's DDR3 product line has enhanced reliability options such as conformal coating for protection against dust, chemicals, extreme temperatures and corrosion. The 30µ" thickness of the gold finger plating ensures better durability and signal transmission quality.

Technologies & Add-On Services	<mark>З0µ"</mark> ЛПЛЛЛ З0µ" Golden Finger		Wide Temperature	Anti-Sulfur Resistors	Conformal Coating	PCB Chamfer
RDIMM	•	•			-	
ECC UDIMM	•	•				<b>A</b>
Non-ECC UDIMM	•	•				
ECC SO-DIMM	•	•				
Non-ECC SO-DIMM	•	•				
Mini-RDIMM	•	•			_	-
Mini-UDIMM	٠	•			_	-

▲: Optional

## Specifications

DDR3								
DIMM Type	RDIMM	ECC UDIMM	Non-ECC UDIMM			Mini-RDIMM	Mini-UDIMM	
Density	1 GB to 32GB		1 GB to	1 GB to 8 GB				
Speed up to (MT/s)		1866					1600	
PCB Height*	Low profile / VLP / ULP		Low profile / VLP	Low profile / ULP	Low profile	Low profile	/ VLP / ULP	
Operating Temperature	0°C to 85°C / -40°C to 85°C							

\* VLP: 0.74", ULP: below 0.74"

Hot Items Ordering Information							
SPEED	SIZE	CHIP	HEIGHT	Ranks	P/N		
Unbuffered Non ECC Module DDR3-1600	4 GB	512x8	1.18"	1	AQ12P64A8BLKOM		
Unbuffered Non ECC Module DDR3-1600	8 GB	512x8	1.18"	2	AQ24P64B8BLKOM		
Unbuffered Non ECC SO-DIMM DDR3-1600	4 GB	512x8	1.18"	1	AW12P6438BLK0M		
Unbuffered Non ECC SO-DIMM DDR3-1600	8 GB	512x8	1.18"	2	AW24P64F8BLK0M		

Product spec and its related information are subject to change without advance notice. Please refer to <u>www.atpinc.com</u> for latest information

v1 022024

© Copyright 2024 ATP Electronics, Inc. All rights reserved.



sales-apac@atpinc.com

The Global Leader in Specialized Storage and Memory Solutions

## WE BUILD WITH YOU

#### ATP TAIWAN (HQ)

## ATP USA

TEL: +886-2-2659-6368 TEL: +1-408-732-5000 sales@atpinc.com

TEL: +49-89-374-9999-0 sales-europe@atpinc.com

ATP EUROPE

ATP JAPAN

TEL: +81-3-6260-0797 sales-japan@atpinc.com ATP CHINA

TEL: +86-21-5080-2220 sales@cn.atpinc.com